8-bit Microcontroller

CMOS LSI

8K-byte Flash ROM / 256-byte RAM / 36-pin



http://onsemi.com

Overview

The LC87F0A08A is an 8-bit microcontroller that, centered around a CPU running at a minimum bus cycle time of 12ns, integrates on a single chip a number of hardware features such as 8K-byte flash ROM, 256-byte RAM, an on-chip debugger, a sophisticated 16-bit timer/counter, a 16-bit timer/counter, a 16-bit timer with a prescaler, a base timer serving as a realtime clock, an asynchronous/synchronous SIO interface, a 12-bit 8-channel AD converter with 12-/8-bit resolution selector, a 20× amplifier, constant-voltage detect interrupt, a comparator, a system clock frequency divider, an internal reset circuit, and a 16-source 9-vector interrupt feature.

Features

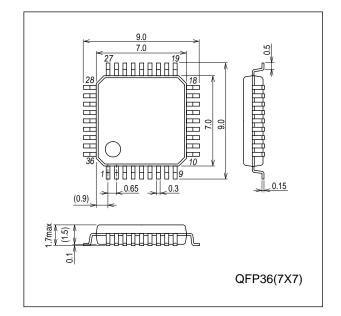
- ■Flash ROM
 - 8192×8 bits
 - Capable of on-board programming with a wide range of supply voltage 2.7 to 5.5V
 - Block-erasable in 128-byte units
 - Writes data in 2-byte units

■RAM

• 256×9 bits

■Package Form

• QFP36 (7×7): Lead-free and halogen-free type



ORDERING INFORMATION

See detailed ordering and shipping information on page 24 of this data sheet.

^{*} This product is licensed from Silicon Storage Technology, Inc. (USA).

■Minimum Bus Cycle Time

- 125ns (8MHz at V_{DD}=2.5V to 5.5V)
- 250ns (4MHz at V_{DD}=2.5V to 5.5V)

Note: The bus cycle time here refers to the ROM read speed.

- ■Minimum Instruction Cycle Time (tCYC)
 - 375ns (8MHz V_{DD}=2.5V to 5.5V)
 - 750ns (4MHz V_{DD}=2.5V to 5.5V)

■Ports

• Normal withstand voltage I/O ports

whose I/O direction specifiable in 1-bit units: 28 (P0n, P1n, P2n, P30 to P32, P70)

• Oscillation/input dedicated ports: 2 (CF1/XT1, CF2/XT2)

• External reset pins: 1 (RES)

• Power supply pins: 4 (V_{SS}1, AV_{SS}, V_{DD}1, V_{DD}2)

• Reference voltage outputs: 1 (VREF)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) × 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)

+ 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs)

+ 8-bit timer/counter with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs) (lower-order 8 bits may be used as PWM outputs)

• Timer A: 16-bit timer

Mode 0: 8-bit timer with an 8-bit programmable prescaler × 2 channels

Mode 1: 16-bit timer with an 8-bit programmable prescaler

- Base timer
 - 1) The input clock is selectable from the subclock (32.768kHz crystal oscillation), low-speed RC oscillator clock, system clock, and timer 0 prescaler output.

(Release of the X'tal HOLD mode is enabled when the subclock or low-speed RC oscillator clock is selected.)

- 2) Provided with an 8-bit programmable prescaler.
- 3) Interrupts programmable in 5 different time schemes.

SIO

- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■AD Converter

- AD converter input port with a 20× operational amplifier (1 channel)
- AD converter input ports (8 channels)
 - 12/8 bits AD converter resolution selectable

■Constant Voltage Detection Interrupt (CVD) Function

- 1) Detects V_{DD} voltage fluctuations and generates an interrupt request.
- 2) The CVD detection level can be selected from 12 levels (2.6V, 2.8V, 3.0V, 3.2V, 3.4V, 3.6V, 3.8V, 4.0V, 4.2V, 4.4V, 4.6V, and 4.8V) through a register.

■Comparator

Comparator input pin (1 channel)

Comparator output pin (1 channel)

Comparator output set high when (comparator input level) < 1.22V

Comparator output set low when (comparator input level) > 1.22V

■Clock Output Function

• Generates clocks with a clock rate of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 of the source oscillation clock that is selected as the system clock.

■Watchdog Timer

- Generates an internal reset on an overflow occurring in the timer running on the low-speed RC oscillator clock (approx. 30kHz) or subclock.
- Operating mode at standby is selectable from 3 modes (continue counting/suspend operation/suspend counting with the count value retained)

■Interrupts

- 16 sources, 9 vectors
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address is given priority.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0/CVD
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/TAL
4	0001BH	H or L	INT3/BT
5	00023H	H or L	T0H/TAH
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	
8	0003BH	H or L	SIO1
9	00043H	H or L	ADC
10	0004BH	H or L	P0

- Priority levels X > H > L
- When interrupts of the same level occur at the same time, an interrupt with a smaller vector address is given priority.
- ■Subroutine Stack Levels: Up to 128levels (the stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

16 bits × 8 bits (5 tCYC execution time)
24 bits × 16 bits (12 tCYC execution time)
16 bits ÷ 8 bits (8 tCYC execution time)
24 bits ÷ 16 bits (12 tCYC execution time)

■Oscillation Circuits

- Internal oscillation circuits
 - 1) Low-speed RC oscillation circuit: For system clock (approx.30kHz)
 - 2) Medium-speed RC oscillation circuit: For system clock (1MHz)
 - 3) Hi-speed RC oscillation circuit: For system clock (8MHz)

■System Clock Divider Function

- Can run on low consumption current.
- Minimum instruction cycle selectable from 375ns, 750ns, 1.5μs, 3.0μs, 6.0μs, 12.0μs, 24.0μs, 48.0μs, and 96.0μs (at 8MHz main clock)

■Internal Reset Circuit

- Power-on reset (POR) function
 - 1) POR reset is generated only at power-on time.
 - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
- Low-voltage detection reset (LVD) function
 - LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - 2) The use/disuse of the LVD function and the low voltage threshold level can be selected from 7 levels (1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V and 4.28V). through option configuration.

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) Having the watchdog timer or LVD function generate a reset
 - (3) Having an interrupt generated
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC and crystal oscillators automatically stop operation.

Note: The low-speed RC oscillator is controlled directly by the watchdog timer; its oscillation in the standby mode is also controlled by the watchdog timer.

- 2) There are five ways of resetting the HOLD mode:
 - (1) Setting the reset pin to the lower level
 - (2) Having the watchdog timer or LVD function generate a reset
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2 and INT4 pins
 - * INTO and INT1 can be used in the level sense mode only.
 - (4) Having an interrupt source established at port 0.
 - (5) Having an interrupt source established in the CVD circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer. (when X'tal oscillation or low-speed RC oscillation is selected).
 - 1) The CF, low-speed, and medium-speed RC oscillators automatically stop operation.

Note: The low-speed RC oscillator is controlled directly by the watchdog timer; its oscillation in the standby mode is also controlled by the watchdog timer.

Note: If the base timer is run with low-speed RC oscillation selected as the base timer input clock source and the X'tal HOLD mode is entered, the low-speed RC oscillator retains the state that is established when the X'tal HOLD mode is entered.

- 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
- 3) There are six ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Having the watchdog timer or LVD function generate a reset
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2, and INT4 pins
 - * INTO and INT1 can be used in the level sense mode only.
 - (4) Having an interrupt source established at port 0
 - (5) Having an interrupt source established in the base timer circuit
 - (6) Having an interrupt source established in the CVD circuit

■On-chip Debugger Function

- Supports software debugging with the IC mounted on the target board.
- Provides 1 channel of on-chip debugger pin.
 DBGP0 (P0)

■Data Security Function

• Protects the program data stored in flash memory from unauthorized read or copy.

Note: This data security function does not necessarily provide absolute data security.

■Development Tools

• On-chip debugger: TCB87 type B + LC87F0A08A or TCB87 Type C (3-wire interface cable) + LC87F0A08A

■Programming Board

6	
Package	Programming board
QFP36(7×7)	W87F0AQ

■Flash ROM Programmer

Vendor		Model	Supported version	Device	
	Single	AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev .02. xx or later	LC87F0A08A	
Flash Support Group, Inc. (FSG)	0	AF9723/AF9723B(Main body) (Including Ando Electric Co., Ltd. models)	-	-	
	Gang	AF9833(Unit) (Including Ando Electric Co., Ltd. models)	·		
Flash Support Group, Inc.	Onboard	AF9101/AF9103(Main body) (FSG)	(1) (1)	1 00750 400 4	
Our company (Note 1)	Single/Gang	SIB87(Interface Driver) (Our company model)	(Note 2)	LC87F0A08A	
0	Single/Gang	SKK/SKK Type B (SANYO FWS)	Application Version 1.16 or later	LC87F0A08A	
Our company	Onboard Single/Gang	SKK-DBG Type B (SANYO FWS)	Chip Data Version 2.13 or later		

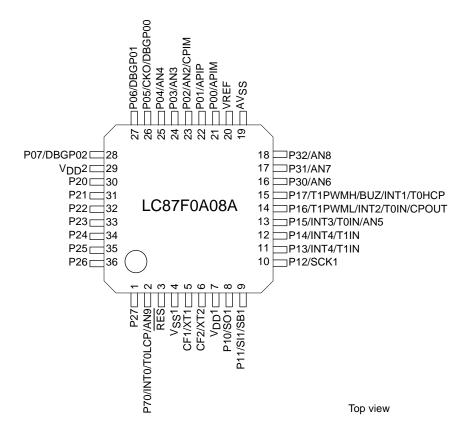
Note1: PC-less standalone onboard programming is possible using the FSG onboard programmer (AF9101/AF9103) and the serial interface driver (SIB87) provided by Our company in pair.

Note2: Dedicated programming device and program are required depending on the programming conditions. Contact Our company or FSG if you have any questions or difficulties regarding this matter.

Package Dimensions

unit : mm (typ) 3162C

Pin Assignment

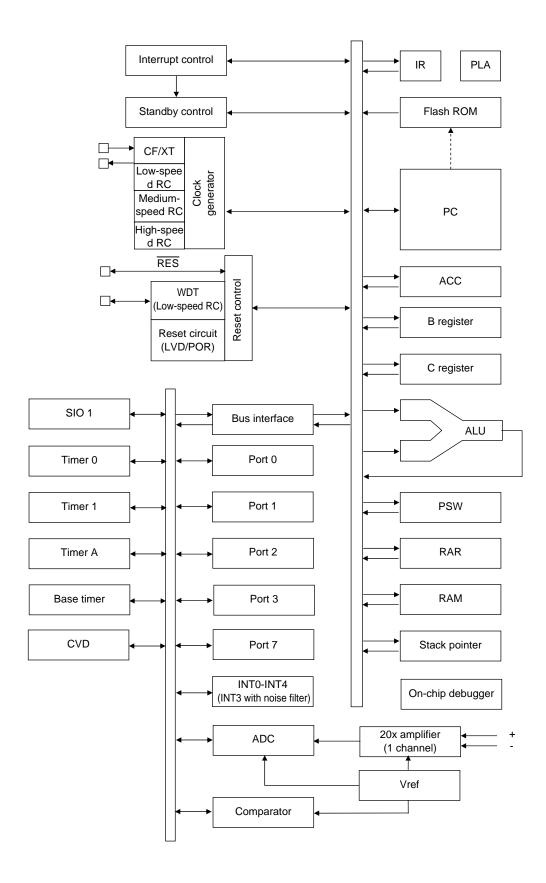


QFP36 (7×7) "Lead-free and halogen-free Type"

QFP36	NAME
1	P27
2	P70/INT0/T0LCP
3	RES
4	V _{SS} 1
5	CF1/XT1
6	CF2/XT2
7	V _{DD} 1
8	P10/SO1
9	P11/SI1/SB1
10	P12/SCK1
11	P13/INT4/T1IN
12	P14/INT4/T1IN
13	P15/INT3/T0IN/AN5
14	P16/T1PWML/INT2/T0IN/CPOUT
15	P17/T1PWMH/BUZ/INT1/T0HCP
16	P30/AN6
17	P31/AN7
18	P32/AN8

QFP36	NAME
19	AV _{SS}
20	VREF
21	P00/AN0
22	P01/AN1
23	P02/AN2/CPIM
24	P03/AN3
25	P04/AN4
26	P05/CKO/DBGP00
27	P06/DBGP01
28	P07/DBGP02
29	V _{DD} 2
30	P20
31	P21
32	P22
33	P23
34	P24
35	P25
36	P26

System Block Diagram



Pin Description

Pin Name	1/0			Desc	cription			Option
V _{SS} 1	-	- power supply pin						No
	_	+ power supply pir						
V _{DD} 1		+ power supply pin						No
V _{DD} 2	-							No
AVSS	-	- power supply pin						No
VREF	0	Reference voltage	output					No
Port 0	I/O	8-bit I/O port						
P00 to P07		I/O specifiable in						
		Pull-up resistors	can be turned o	n and off in 1-bit	units.			
		Pin functions Page (AND) Page	(ANIA) AD		··· 00			
		P00 (AN0), P01 (•	ai amplitier		Vaa
		P02: AD converte		-	iput (CPIIVI)			Yes
		P03: AD converte P04: AD converte		-				
		P05: System clos		-	DBGP00)			
		P06: On-chip del			220. 00)			
		P07: On-chip del		•				
Port 1	I/O	• 8-bit I/O port	00 1 (,				
P10 to P17	1	I/O specifiable in	1-bit units.					
		Pull-up resistors	can be turned o	n and off in 1-bit	units.			
		Current controlla	ble in 1-bit units					
		5mA (default), 10	mA, 15mA, no o	current control				
		Pin functions						
		P10: SIO1 data o	-					
		P11: SIO1 data i		utput				P10, P11
		P12: SIO1 clock					. /	options
		P13, P14: INT4 ii	-	-	event input/timei	* 0L capture inpu	ut/	not available
)H capture input		t/timer Ollegate	una immust/		
		P15: INT3 input(er input port (AN	-	ийшнег он сарц	ire iriput/		
		P16: Timer 1 PW		•	ease input/timer 0	event input/		P12 to P17
			· ·	parator output (C	•			options
		P17: Timer 1 PW			•	se input/timer 0H	d capture input	available
		Interrupt acknow	-		•	·		
			Disire	E-Ilia -	Rising &	Hilmoni	Linus	
			Rising	Falling	Falling	H level	L level	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
		INT4	enable	enable	enable	disable	disable	
Port 2	I/O	• 8-bit I/O port	4 1 2					
		I/O specifiable in		n and aff in 1 bit	unita			Vac
		Pull-up resistorsCurrent controlla			units.			Yes
		5mA (default), 10						
Port 3	I/O	• 3-bit I/O port		Ca.TOTIC COTICO				
. 51. 0	,,,	I/O specifiable in	1-bit units.					
		Pull-up resistors		n and off in 1-bit	units.			
		Pin functions						Yes
		P30: AD convert	er input port (AN	16)				
		P31: AD converter input port (AN7)						
		P32: AD convert	er input port (AN	18)				

Continued on next page.

Continued from preceding page.

Pin Name	I/O			Desc	cription				Option
Port 7 P70	I/O	-	t/HOLD release	on and off.	apture input/AD	converter input	port (AN9)		No
		Interrupt acknow	Rising	Falling	Rising & Falling	H level	L level		
		INT0	enable	enable	disable	enable	enable		
RES	I/O	External reset inp	out/internal rese	t output pin					No
CF1/XT1	I	Pin functions	Ceramic oscillator/32.768kHz crystal oscillator input pin						No
CF2/XT2	I/O	Ceramic oscilla Pin functions General-purpose		crystal oscillator	output pin				No

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P10 to P11	-	No	CMOS	Programmable
P12 to P177	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P27	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P32	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable

Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = V_{SS}2 = 0V$

Parameter		Cymphol	Din/Demarks	Conditions			Specific	ation	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Maximum supply voltage		V _{DD} max	V _{DD} 1=V _{DD} 2			-0.3		+6.5	
Input voltage		VI	CF1, CF2			-0.3		V _{DD} +0.3	V
	out/output ltage	V _{IO}	Ports 0, 1, 2 Ports 3, 7			-0.3		V _{DD} +0.3	
	Peak output current Average output current	IOPH(1)	Ports 0, 3	CMOS output type selected Per 1 applicable pin		-10			
High level output current		IOPH(2)	Ports 1, 2	CMOS output type selected Per 1 applicable pin		-20			
		IOMH(1)	Ports 0, 3	CMOS output type selected Per 1 applicable pin		-7.5			
el outpu	(Note 1-1)	IOMH(2)	Ports 1, 2	CMOS output type selected Per 1 applicable pin		-15			
igh leve	Total output current	ΣΙΟΑΗ(1)	Ports 0, 1, 3	Total current of all applicable pins		-30			
I		ΣΙΟΑΗ(2)	Port 2	Total current of all applicable pins		-30			mA
		ΣΙΟΑΗ(3)	Ports 0, 1, 2, 3	Total current of all applicable pins		-50			
	Peak output	IOPL(1)	Ports 0, 3	Per 1 applicable pin				20	
rent	current	IOPL(2)	Ports 1, 2	Per 1 applicable pin				20	
Low level output current		IOPL(3)	Port 7	Per 1 applicable pin				10	
utbui	Average	IOML(1)	Ports 0, 3	Per 1 applicable pin				15	Ī
<u>o</u>	output current	IOML(2)	Ports 1, 2	Per 1 applicable pin				15	
<u> </u>	(Note 1-1)	IOML(3)	Port 7	Per 1 applicable pin				7.5	
Lo	Total output current	ΣIOAL(1)	Ports 0, 1, 2, 3, 7	Total current of all applicable pins				80	
	owable power sipation	Pd max (1)	QFP36	Ta=-40 to +85°C Package alone					
		Pd max (2)		Ta=-40 to +85°C Mounted on thermal resistance test board (Note 1-2)					mW
	perating ambient	Topr				-40		+85	
Sto	orage ambient	Tstg				-55		+125	°C

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Note 1-2: Thermal resistance test board used conforms to SEMI (size: 76.1×114.3×1.6tmm, glass epoxy board).

Allowable Operating Conditions at Ta = -40°C to +85°C, $V_SS1 = V_SS2 = 0V$

Doromotor	Cymphol	Din/Damarka	Conditions			Specific	ation		
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Operating supply	V _{DD} (1)	V _{DD} 1=V _{DD} 2	$0.367 \mu s \le tCYC \le 200 \mu s$		2.5		5.5		
voltage (Note 2-1)	V _{DD} (2)		0.735μs ≤ tCYC ≤ 200μs		2.5		5.5		
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2	RAM and register contents sustained in HOLD mode		2.0				
High level input voltage	V _{IH} (1)	Ports 0, 1, 2, 3 P70		2.5 to 5.5	0.3V _{DD} +0.7		V_{DD}	V	
	V _{IH} (4)	CF1, RES		2.5 to 5.5	0.75V _{DD}		V_{DD}		
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3 P70		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4		
				2.5 to 4.0	V_{SS}		0.2V _{DD}		
	V _{IL} (4)	CF1, RES		2.5 to 5.5	V_{SS}		0.25V _{DD}		
Instruction cycle	tCYC			2.7 to 5.5	0.245		200		
time	(Note 2-2)			2.5 to 5.5	0.367		200	μS	
•				2.5 to 5.5	0.735		200		
External system	FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12		
clock frequency			System clock frequency division ratio=1/1 External system clock duty=50±5%	2.5 to 5.5	0.1		8	MHz	
Oscillation frequency range	FmCF(1)	CF1, CF2	8MHz ceramic oscillation See Fig. 1.	2.5 to 5.5		8			
(Note 2-3)	FmCF(2)	CF1, CF2	4MHz ceramic oscillation See Fig. 1.	2.5 to 5.5		4			
	FmMRC		1/2 of high-speed RC oscillation frequency (RCCTD=0) (Note 2-4)	2.5 to 5.5	7.44	8.0	8.56	MHz	
	FmRC		Internal medium-speed RC oscillation	2.5 to 5.5	0.5	1.0	2.0		
	FmSRC	RC Internal low-speed RC oscillation 2.5 to 5.5 15 30	60	kHz					
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.5 to 5.5		32.768		KΠZ	

- Note 2-1: $V_{\mbox{DD}}$ must be held greater than or equal to 2.7V in the flash ROM onboard programming mode.
- Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.
- Note 2-3: See Tables 1 and 2 for the oscillation constants.
- Note 2-4: An oscillation stabilization time of $100\mu s$ or longer must be provided before switching the system clock source after the state of the high-speed RC oscillation circuit is switched from "oscillation stopped" to "oscillation enabled".

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = 0V$

				- 55				
D	0	Di-/D	One Pri			Specifica	ition	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3 Port 7, RES	Output disabled Pull-up resistor off VIN=VDD (including output TR's off leakage current)	2.5 to 5.5			1	
	I _{IH} (2)	CF1	V _{IN} =V _{DD}	2.5 to 5.5			15	1
Low level input current	I _{IL} (1)	Ports 0, 1, 2, 3 Port 7, RES	Output disabled Pull-up resistor off VIN=VSS (including output TR's off leakage current)	2.5 to 5.5	-1			μА
	I _{IL} (2)	CF1	V _{IN} =V _{SS}	2.5 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)		I _{OH} =-0.2mA	2.5 to 5.5	V _{DD} -0.4			
	V _{OH} (3)	Ports 1, 2	I _{OH} =-6mA	4.5 to 5.5	V _{DD} -1			
	V _{OH} (4)		I _{OH} =-1.0mA	2.5 to 5.5	V _{DD} -0.4			.,
Low level output	V _{OL} (1)	Ports 0, 1, 2, 3	I _{OL} =10mA	4.5 to 5.5			1.5	V
voltage	V _{OL} (2)		I _{OL} =1.0mA	2.5 to 5.5			0.4	
	V _{OL} (3)	P70	I _{OL} =8mA	4.5 to 5.5			1.5	
	V _{OL} (4)		I _{OL} =1.0mA	2.5 to 5.5			0.4	
Constant current operation enabled pin voltage	VOCC	Ports 1, 2		2.5 to 5.5	1		V _{DD} -1.0	V
Constant current	ILED(1)	Ports 1, 2	Per 1 applicable pin only	2.7 to 5.5	4	5	6	
port current (5mA setting)	ILED(2)		ON time V _O =1.0 to (V _{DD} -1.0)	2.5 to 2.7	3	5	6	
Constant current	ILED(3)			2.7 to 5.5	8	10	12	
port current (10mA setting)	ILED(4)	_		2.5 to 2.7	6	10	12	mA
Constant current	ILED(5)			2.7 to 5.5	LED	O(1)+LED(3	3)	
port current (15mA setting)	ILED(6)			2.5 to 2.7	LEC)(2)+LED(4	·)	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	kΩ
	Rpu(2)	Port 7		2.5 to 4.5	18	50	230	KS 2
Hysteresis voltage	VHYS(1)	Ports 0, 1, 2, 3 P70 RES		2.5 to 5.5		0.1V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test VIN=VSS f=1MHz Ta=25°C	2.5 to 5.5		10		pF

SIO1 Serial I/O Characteristics (Note 4-1)

	Parameter Symbol Pin/ Conditions			O and distance			Speci	fication		
	,	Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ik	Frequency	tSCK(1)	SCK1(P12)	• See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(1)			2.5 to 5.5	1			
Serial clock	ln	High level pulse width	tSCKH(1)				1			tCYC
Serial	ck	Frequency	tSCK(2)	SCK1(P12)	CMOS output type selected See Fig. 5.		2			
	Output clock	Low level pulse width	tSCKL(2)			2.5 to 5.5	1/2			tSCK
	nO	High level pulse width	tSCKH(2)					1/2		ison
Serial input	Da	ta setup time	tsDI(1)	SI1(P11), SB1(P11)	Specified with respect to rising edge of SIOCLK. See Fig. 5.	0.511.5.5	0.05			
Serial	Da	ta hold time	thDI(1)			2.5 to 5.5	0.05			
Serial output	Ou	tput delay time	tdDO(1)	SO1(P10), SB1(P11)	Specified with respect to falling edge of SIOCLK Specified as the time up to the beginning of output change in open drain output mode. See Fig. 5.	2.5 to 5.5			(1/3)tCYC +0.08	μѕ

Note 4-1: These specifications are theoretical values. Margins must be allowed according to the actual operating conditions.

Pulse Input Conditions at Ta = -40°C to +85°C, $V_SS1 = V_SS2 = 0V$

		B: /B	0 11			Speci	fication	
Iigh/low level tPIH(1)	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
High/low level pulse width	` '	INT0(P70), INT1(P71), INT2(P16), INT4(P13, P14)	Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled.	2.5 to 5.5	1			
	` '	INT3(P15) when noise filter time constant is 1/1	Interrupt source flag can be set. Event inputs for timer 0 are 2.5 to 5.5 enabled.		2			tCYC
	` '	INT3(P15) when noise filter time constant is 1/32	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.5 to 5.5	64			
	` '	INT3(P15) when noise filter time constant is 1/128	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.5 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	2.5 to 5.5	200			μS

AD Converter Characteristics at $V_{SS}1 = AV_{SS} = 0V$

<12bits AD Converter Mode/Ta = -40°C to +85°C >

Danamatan	O. mak al	Pin/Remarks	O a malikia ma			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN2(P02)		3.0 to 5.5		12		bit
Absolute accuracy	ET	AN3(P03) AN4(P04)	(Note 6-1)	3.0 to 5.5			±16	LSB
Conversion time	TCAD	AN5(P15)	See conversion time calculation	4.0 to 5.5	32		115	
		AN6(P30) AN7(P31)	method. (Note 6-2)	3.0 to 5.5	64		115	μS
Analog input voltage range	VAIN	AN8(P32) AN9(P70)		3.0 to 5.5	V _{SS}		VREF	٧
Analog port	IAINH	(Note 6-3)	VAIN=V _{DD}	3.0 to 5.5			1	
input current	IAINL	, ,	VAIN=V _{SS}	3.0 to 5.5	-1			μА

<8bits AD Converter Mode/Ta = -40°C to +85°C >

D	0	Pin/Remarks	O a madition a			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN2(P02)		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN3(P03) AN4(P04)	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN5(P15)	See "Conversion time	4.0 to 5.5	20		90	
		AN6(P30) AN7(P31)	calculation method". (Note 6-2)	3.0 to 5.5	40		90	μЅ
Analog input voltage range	VAIN	AN8(P32) AN9(P70)		3.0 to 5.5	V _{SS}		VREF	V
Analog port	IAINH	(Note 6-3)	VAIN=V _{DD}	3.0 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μА

<Conversion time calculation method>

12bits AD Converter Mode: TCAD(Conversion time) = $((52/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 8bits AD Converter Mode: TCAD(Conversion time) = $((32/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$

< Recommended Operating Conditions>

External oscillation	Operating supply voltage range	System division ratio	Cycle time	AD division ratio	AD conversion time (TCAD)		
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD	
OF OMUL-	4.0V to 5.5V	1/1	375ns	1/8	52.3μs	32.3µs	
CF-8MHz	3.0V to 5.5V	1/1	375ns	1/16	104.5μs	64.5μs	
CF-4MHz	3.0V to 5.5V	1/1	750ns	1/8	104.5μs	64.5µs	

Note 6-1: The quantization error (±1/2LSB) is excluded from the absolute accuracy. The absolute accuracy is measured when no change occurs in the I/O state of the pins that are adjacent to the analog input channel during AD conversion processing.

Note 6-2: The conversion time refers to the interval from the time a conversion starting instruction is issued till the time the complete digital value against the analog input value is loaded in the result register.

The conversion time is twice the normal value when one of the following conditions occurs:

- The first AD conversion executed in the 12-bit AD conversion mode after a system reset
- The first AD conversion executed after the AD conversion mode is switched from 8-bit to 12-bit AD conversion mode

Note 6-3: See section 8, "20× amplifier characteristics", for analog channel 0 (20× amplifier output).

Reference Voltage Generator Circuit (VREF) Characteristics

at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = AV_{SS} = 0V$

Description	O. made al	Dia /Damania	0			Specifica	ation	
Parameter	Symbol	Pin/Remarks	Conditions V _{DD} [V]		min	typ	max	unit
VREF voltage	VREFVO	VREF	• Ta=-40 to +85°C	2.5 to 4.0	V _{DD} -0.1		V_{DD}	
accuracy		(Note 7-2)		4.0 to 5.5	3.92	4.00	4.08	V
			• Ta=-40 to +60°C	4.5 to 5.5	3.96		4.04	
VREF output current	VREFIO		• Ta=-40 to +85°C	2.5 to 5.5	V _{SS}		1	mA
Operation stabilization time (Note 7-1)	tVREFW			2.5 to 5.5			10	μS

Note 7-1: Refers to the interval between the time VRONZ is set to 0 and the time operation gets stabilized.

Note 7-2: An external $4.7\mu F$ capacitor must be connected to the VREF pin to stabilize the VREF voltage.

20x Amplifier Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, VSS1 = AVSS = 0V

<u></u>				o, . DD -	00	• •		
	0 1 1	D: (D	0 - 171			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Amplifier gain	APGAIN See Fig. 7.	P00/APIM P01/APIP	• Ta=-40 to +85°C • VREF=4.0V			20		
Operation stabilization time (Note 8-1)	tAPW		• P01=0V, P00≤0V or P00=0V, P01≥0V				1.0	μЅ
Amplifier input voltage full scale (Note 8-1)	VAPFUL			5.0	0.16		0.19	V
Amplifier input	VAPIM	P00/APIM	P01/APIP=0V		-VAPFUL		0	
voltage range	VAPIP	P01/APIP	P00/APIM=0V		0		VAPFUL	
Amplifier input port	IAPINL	P00/APIM	P00/APIM=V _{SS} -0.2V		-1			
input current	IAPINH	P01/APIP	P01/APIP=V _{DD}				1	μА

Note 8-1: Refers to the interval between the time APON is set to 1 and the time operation gets stabilized.

Comparator Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = AV_{SS} = 0V$

				י טט־	'DD	•		
		5: (5				Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Comparator threshold voltage (Note 9-1)	VCMVT	P02/CPIM		2.5 to 5.5	1.12	1.22	1.32	V
Common mode input voltage range	VCMIN			2.5 to 5.5	V _{SS}		V _{DD} -1.5	V
Offset voltage	VOFF		Within common mode input voltage range	2.5 to 5.5		±10	±30	mV
Response time	tRT		Within common mode input voltage range Input amplitude=100mV Overdrive=50mV	2.5 to 5.5		200	600	ns
Operation stabilization time (Note 9-2)	tCMW			2.5 to 5.5			1.0	μs

Note 9-1: Comparator output=High level when (P02/CPIM voltage) < VCMVT

 $Comparator\ output = Low\ level\ when\ (P02/CPIM\ voltage) > (VCMVT\ + VOFF)$

Note 9-2: Refers to the interval between the time CPONZ is set to 0 and the time operation gets stabilized.

Power-on Reset (POR) Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = AV_{SS} = 0V$

						Specific	ation	
Parameter	Symbol	Pin / Remarks	Conditions	Option Selected Voltage	min	typ	max	unit
POR release	PORRL		Option selected	1.67V	1.55	1.67	1.79	
voltage			(Note 10-1)	1.97V	1.85	1.97	2.09	
				2.07V	1.95	2.07	2.19	
				2.37V	2.25	2.37	2.49	
				2.57V	2.45	2.57	2.69	V
				2.87V	2.75	2.87	2.99	V
				3.86V	3.73	3.86	3.99	
				4.35V	4.21	4.35	4.49	
Detection voltage unpredictable area	POUKS		See Fig. 8. (Note 10-2)			0.7	0.95	
Power supply rise time	PORIS		Power startup time from V _{DD} =0V to 1.6V				100	ms

Note 10-1: The POR release voltage can be selected from 8 levels when the low-voltage detection feature is deselected.

Note 10-2: There is an unpredictable area before the transistor starts to turn on.

Low-voltage Detection (LVD) Reset Characteristics

at Ta = -40°C to +85°C, VSS1 = AVSS = 0V

						Specifica	ation	
Parameter	Symbol	Pin/Remarks	Conditions	Option Selected Voltage	min	typ	max	uni
LVD reset voltage	LVDET		Option selected	1.91V	1.81	1.91	2.01	
(Note 11-2)			See Fig. 9.	2.01V	1.91	2.01	2.11	
			(Note 11-1) (Note 11-3)	2.31V	2.21	2.31	2.41	
			(Note 11-3)	2.51V	2.41	2.51	2.61	٧
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD voltage	LVHYS			1.91V		55		
hysteresis				2.01V		55		
				2.31V		55		
				2.51V		55		m
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unpredictable area	LVUKS		See Fig. 9. (Note 11-4)			0.7	0.95	٧
Minimum low voltage detection width (response sensitivity)	TLVDW		LVDET-0.5V See Fig. 10.		0.2			m

Note 11-1: The LVD reset voltage can be selected from 7 levels when the low-voltage detection feature is selected.

Note 11-2: The hysteresis voltage is not included in the LVD reset voltage specification value.

Note 11-3: There are cases when the LVD reset voltage specification value is exceeded when a greater change in the output level or large current is applied to the port.

Note 11-4: There is an unpredictable area before the transistor starts to turn on.

Constant Voltage Detection (CVD) Interrupt Characteristics

at Ta = -40 to +85°C, $V_{SS}1 = AV_{SS} = 0V$

						Specifica	ation	
Parameter	Symbol	Pin/Remarks	Conditions	Register Selected Voltage	min	typ	max	unit
CVD detection	CVDET		Register selected	2.6V	2.5	2.6	2.7	
voltage			(Note 12-1)	2.8V	2.7	2.8	2.9	
(Note 12-2)			(Note 12-3)	3.0V	2.9	3.0	3.1	
				3.2V	3.1	3.2	3.4	
				3.4V	3.3	3.4	3.6	
				3.6V	3.5	3.6	3.8	
				3.8V	3.7	3.8	4.0	V
				4.0V	3.9	4.0	4.2	
				4.2V	4.1	4.2	4.4	
				4.4V	4.3	4.4	4.6	
				4.6V	4.5	4.6	4.8	
				4.8V	4.7	4.8	5.0	
CVD detection	CVHYS			2.6V		50		
voltage hysteresis				2.8V		50		
				3.0V		50		
				3.2V		50		
				3.4V		50		
				3.6V		50		l
				3.8V		50		mV
				4.0V		50		
				4.2V		50		
				4.4V		50		
				4.6V		50		
				4.8V		55		
Detection voltage	CVUKS		(Note 12-4)			0.7	0.95	٧
unpredictable area Minimum CVD detection width (response	TCVDW		CVDET-0.5V		0.8			ms
sensitivity) Operation stabilization time (Note 12-5)	tCVDON		V _{DD} =2.5 to 5.5V				100	μѕ

- Note 12-1: The CVD detection voltage can be selected from 16 levels.
- Note 12-2: The hysteresis voltage is not included in the CVD detection voltage specification value.
- Note 12-3: There are cases when the CVD detection voltage specification value is exceeded when a greater change in the output level or large current is applied to the port.
- Note 12-4: There is an unpredictable period before the CVD-related transistor starts to turn on.
- Note 12-5: Refers to the interval between the time CVDRUN is set to 1 and the time operation gets stabilized.

Consumption Current Characteristics at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = 0V$

Parameter	Symbol	Pin/	Conditions			Specifi	cation	1
i diametei	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1 =V _{DD} 2	FmCF=8MHz ceramic oscillation mode System clock set to 8MHz mode Internal low-/medium-speed RC oscillation	4.5 to 5.5		5.5	11.3	
(Note 13-1) (Note 13-2)			stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		3.4	9.0	
	IDDOP(2)		FmCF=4MHz ceramic oscillation mode System clock set to 4MHz mode Internal low-/medium-speed RC oscillation	4.5 to 5.5		2.8	6.8	
			stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		2.1	5.4	mA
	IDDOP(3)		FsX'tal=32.768kHz crystal oscillation mode Internal low-speed RC oscillation stopped System clock set to internal medium-speed	4.5 to 5.5		0.6	1.9	MA
			RC oscillation mode Internal high-speed RC oscillation stopped Frequency division ratio set to 1/2	2.5 to 4.5		0.3	1.4	
	IDDOP(4)		FsX'tal=32.768kHz crystal oscillation mode Internal low-/medium-speed RC oscillation stopped	4.5 to 5.5		5.0	9.9	
IDDOP(5)			System clock set to internal high-speed RC oscillation mode Frequency division ratio set to 1/1	2.5 to 4.5		3.5	8.6	
	IDDOP(5)		External oscillation FsX'tal/FmCF stopped System clock set to internal low-speed RC oscillation mode	4.5 to 5.5		21.3	89.4	
			Internal medium-speed RC oscillation stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		13.6	64.8	
	IDDOP(6)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz mode Internal low-/medium-speed RC oscillation	4.5 to 5.5		22.8	101.5	μА
			stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/2	2.5 to 4.5		10.9	70.0	
HALT mode consumption current (Note 13-1)	IDDHALT(1)	V _{DD} 1 =V _{DD} 2	HALT mode • FmCF=8MHz ceramic oscillation mode • System clock set to 8MHz mode • Internal low-/medium-speed RC oscillation	4.5 to 5.5		2.0	3.2	
(Note 13-2)			stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		1.0	2.3	
	IDDHALT(2)		HALT mode • FmCF=4MHz ceramic oscillation mode • System clock set to 4MHz mode	4.5 to 5.5		1.3	2.2	
			Internal low-/medium-speed RC oscillation stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		0.6	1.5	mA
	IDDHALT(3)		HALT mode • FsX'tal=32.768kHz crystal oscillation mode • Internal low-speed RC oscillation stopped	4.5 to 5.5		0.3	1.2	
			System clock set to internal medium-speed RC oscillation mode Internal high-speed RC oscillation stopped Frequency division ratio set to 1/2	2.5 to 4.5		0.2	0.8	

Note 13-1: The consumption current value includes none of the currents that flow into the output transistors and internal pull-up resistors.

Note 13-2: Unless otherwise specified, the consumption current for the LVD circuit is not included.

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Dorometer	Cumbal	Pin/	Conditions			Specific	cation	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 13-1)	IDDHALT(4)	V _{DD} 1 =V _{DD} 2	HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal low-/medium-speed RC oscillation stopped	4.5 to 5.5		1.6	2.2	
(Note 13-2)			System clock set to internal high-speed RC oscillation mode Frequency division ratio set to 1/1	2.5 to 4.5		1.1	1.8	
	IDDHALT(5)		HALT mode External oscillation FsX'tal/FmCF stopped System clock set to internal low-speed RC oscillation mode	4.5 to 5.5		5.6	43	
			Internal medium-speed RC oscillation stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/1	2.5 to 4.5		3.3	30.4	^
	IDDHALT(6)	IDDHALT(6) HALT mode FSX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz mode Internal low-/medium-speed RC oscillation		4.5 to 5.5		12.0	69.8	μА
			stopped Internal high-speed RC oscillation stopped Frequency division ratio set to 1/2	2.5 to 4.5		4.4	44.7	
HOLD mode	IDDHOLD(1)	$V_{DD}1$	HOLD mode	4.5 to 5.5		0.024	41.0	
consumption current		=V _{DD} 2		2.5 to 4.5		0.010	27.2	
(Note 13-1)	IDDHOLD(2)		HOLD mode	4.5 to 5.5		2.9	30.2	
(Note 13-2)			LVD option selected	2.5 to 4.5		2.3	22.3	
Timer HOLD	IDDHOLD(3)	V _{DD} 1	Timer HOLD mode	4.5 to 5.5		9.9	63.2	
mode		=V _{DD} 2	FsX'tal=32.768kHz crystal oscillation mode	2.5 to 4.5		3.2	39.6	μА
consumption current	IDDHOLD(4)		Timer HOLD mode	4.5 to 5.5		2.1	31.6	μπ
(Note 13-1)			FmSRC=30kHz internal low-speed RC oscillation mode	2.5 to 4.5		1.2	8.4	
(Note 13-2)	IDDHOLD(5)		Timer HOLD mode • FmSRC=30kHz internal low-speed RC	4.5 to 5.5		29.3	110.2	
			oscillation mode CVD active mode	2.5 to 4.5		20.1	86.3	

Note 13-1: The consumption current value includes none of the currents that flow into the output transistors and internal pull-up resistors.

Note 13-2: Unless otherwise specified, the consumption current for the LVD circuit is not included.

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = AV_{SS} = 0V$

	3 3						55			
D	O. mak al	Dia /Danasala	O andisiana		Specification					
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Onboard programming current	IDDFW(1)	V _{DD} 1	Excluding power dissipation in the microcontroller block	2.7 to 5.5		5	10	mA		
Programming	tFW(1)		Erase mode	0.74- 5.5		20	30	ms		
time	tFW(2)		Programming mode	2.7 to 5.5		40	60	μs		

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

■MURATA Manufacturing Co., Ltd.

Nominal		0 11 4 11	Circuit Constant				Operating	Oscillation Stabilization Time		
Frequency	Type lency	Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks
4MHz	SMD	CSTCR4M00G53-R0	(10)	(10)	Open	3.3k	2.5 to 5.5	0.03		C1 and C2
8MHz	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	1.5k	2.5 to 5.5	0.02		integrated type

Characteristics of a Sample Subsystem Clock Oscillation Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit that Uses a Crystal Oscillator

■EPSON TOYOCOM

Nominal	T		Circuit Constant				Operating	Oscillation Stabilization Time		
Frequency Type	Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	$\operatorname{Rd} olimits_{[\Omega]} olimits$	Voltage Range [V]	typ [ms]	max [ms]	Remarks	
32.768kHz	SMD	MC-306	7	7	Open	330k	2.5 to 5.5	0.85		CL value applied: 7pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 3):

- Till the oscillation gets stabilized after the instruction for starting the subclock oscillation circuit is executed
- Till the oscillation gets stabilized after the HOLD mode is released.

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

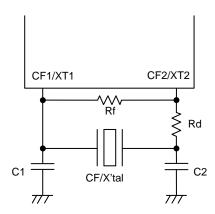


Figure 1 CF/XT Oscillator Circuit

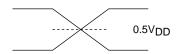
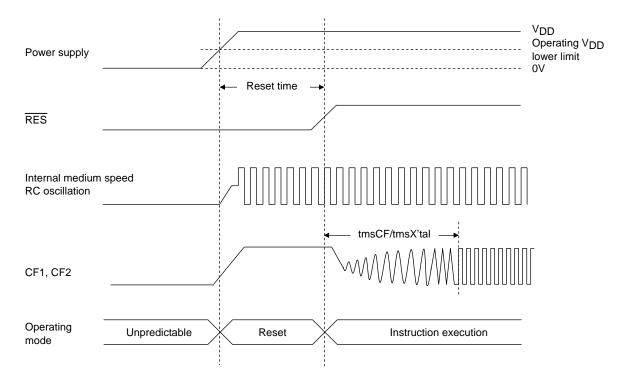
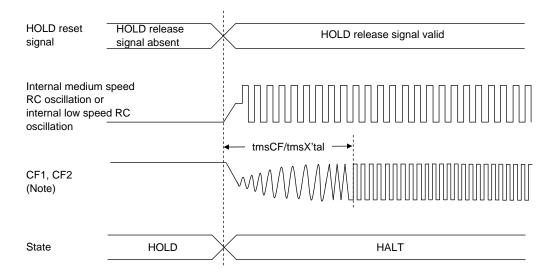


Figure 2 AC Timing Measurement Point



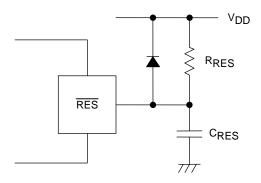
Reset Time and Oscillation Stabilization Time



HOLD Release Signal and Oscillation Stabilization Time

Note: When an external oscillation circuit is selected.

Figure 3 Oscillation Stabilization Time



Note:

The external circuit for reset may vary depending on the usage of POR and LVD. See "Reset Function" in the user's manual.

Figure 4 Sample Reset Circuit

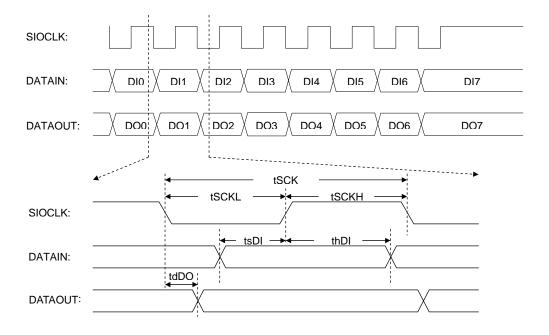


Figure 5 Serial I/O Waveform

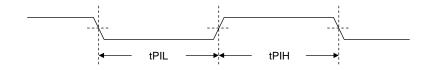


Figure 6 Pulse Input Timing Signal Waveform

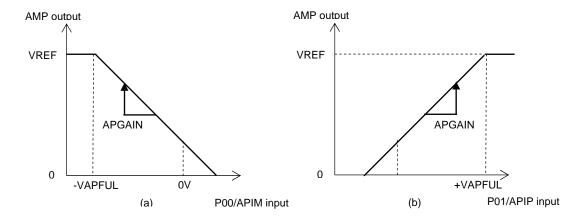


Figure 7 20× Amplifier Characteristics

- (a) When P01/APIP is 0V, P00/APIM \leq 0V.
- (b) When P00/APIM is 0V, P01/APIP \geq 0V.

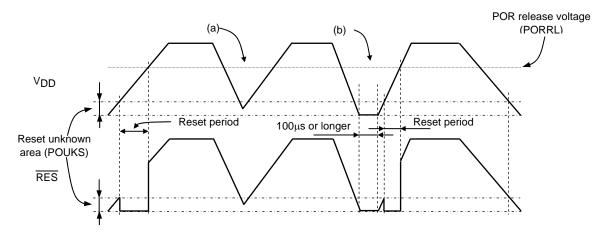


Figure 8 Example of POR Only (LVD Deselected) Mode Waveforms (at Reset Pin with RRES Pull-up Resistor Only)

- The POR function generates a reset only when the power voltage goes up from the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit as shown below.
- A reset is generated only when the power level goes down to the V_{SS} level as shown in (b) and power is turned on again after this condition continues for $100\mu s$ or longer.

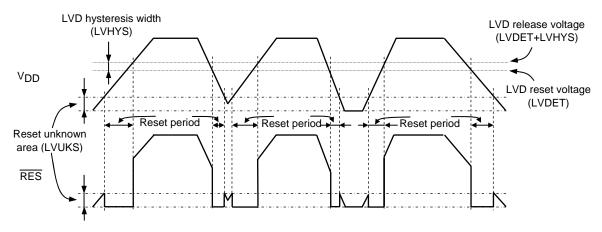


Figure 9 Example of POR + LVD Mode Waveforms (at Reset Pin with RRES Pull-up Resistor Only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

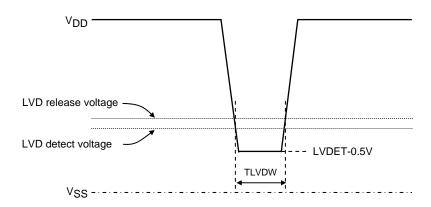


Figure 10 Minimum Low Voltage Detection Width (Example of Voltage Sag/Fluctuation Waveform)

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)			
LC87F0A08AU-EB-TLM-H	QFP36(7X7) (Pb-Free / Halogen Free)	1000 / Tape & Reel			
LC87F0A08AUEB-NH	QFP36(7X7) (Pb-Free / Halogen Free)	1000 / Tape & Reel			

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